

**2016 INTERNATIONAL SYMPOSIUM ON
3D POWER ELECTRONICS INTEGRATION & MANUFACTURING**

	13-Jun-16 MONDAY	14-Jun-16 TUESDAY	15-Jun-16 WEDNESDAY	
8:00 AM - 9:55 AM	TUTORIALS THE WORLD OF PACKAGING TECHNOLOGIES and THE CRITICAL ISSUES [TBD] <i>by Dr Patrick Mc Clusky</i> [TBD] <i>by Dr Guo-Quan (GQ) Lu</i> <i>Additive Manufacturing for Power Electronics</i> <i>by Dr Douglas Hopkins</i>	PLENNARY ROAD MAPPING (Ernier Parker, Chair) Break MULTIPHYSICS MODELING & SIMULATION (Zhengxian Liang, Chair)	MANUFACTURABILITY (Jared Hornberger, Chair)	
9:55 AM - 10:20 PM			Break	Break
10:20 AM - 12:15PM			QUALITY & RELIABILITY (TBD, Chair)	
12:15 PM - 1:15 PM	Lunch - Tutorial Attendees (Networking)	Lunch (Networking)	Lunch (Networking)	
1:15 PM - 3:10 PM	ADDITIVE MANUFACTURING (TBD, Chair)	MATERIALS (TBD, Chair)	PASSIVE COMPONENTS (Kai Ngo, Chair)	
3:10 PM - 3:35 PM	Break	Break	Break (Networking) NCSU LAB TOURS PREES PACAGING ADD MFG & LOGISTICS CTR	
3:35PM - 5:30PM	THERMAL MAAGEMENT & SYSTEMS INTEGRATION (Sreekant Narumanchi, Chair)	EMBEDDED COMPONENTS (TBD, Chair)		
5:30 PM - 7:30 PM	WELCOME RECEPTION DIALOGUE PRESENTATIONS & VENDOR EXHIBITS	NETWORKING RECEPTION DIALOGUE PRESENTATIONS & VENDOR EXHIBITS		